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## GUJARAT TECHNOLOGICAL UNIVERSITY

**BE - SEMESTER-VIII(NEW) EXAMINATION - SUMMER 2019** 

6h	L Seat C	Det = SERVESTER = V III(INE W) EXAMINATION = SUMMERDetails = Details = De	. 2019 1 <i>5/05/3</i> 010
Subject Code:2105901 Date:15/05/2019			
Subj	ject Na	ame:Nanolithography	
Time:10:30 AM TO 01:00 PM Total Mai			l Marks: 70
Instru	ictions:		
	1. A	ttempt all questions.	
	2. M	lake suitable assumptions wherever necessary.	
	<b>3.</b> Г	igures to the right mulcate full marks.	
			MARKS
0.1	(a)	Define: Photoresist.	03
	(b)	Differentiate between Positive and Negative photoresists.	04
	(c)	Explain basic process of Photolithography.	07
Q.2	(a)	What is resist soft bake?	03
C.	<b>(b)</b>	Explain spin coating of resist.	04
	(c)	Explain Acid-catalyzed DUV resist	07
		OR	
	(c)	Explain Adhesion Promotion.	07
Q.3	(a)	Write basic principle of nanoimprint lithography.	03
	<b>(b</b> )	Explain fabrication of mold for nanoimprint lithography.	04
	( <b>c</b> )	Write note on X-ray Lithography.	07
		OR	
Q.3	<b>(a)</b>	What is residual layer?	03
	<b>(b)</b>	Explain separating the mold and resists after nanoimprint.	04
	(c)	Write note on Nano-imprint Lithography.	07
Q.4	(a)	Write basic process of XRL.	03
	(b)	Give differences between High Resolution and Deep XRL.	04
	(c)	Write a short note on X-ray source used for XRL.	07
0.4	<b>(a)</b>	What is resist hard bake?	03
<b>X</b>	(b)	Explain historical background leading to nanoimprint lithograp	hv. <b>04</b>
	(c)	Write applications of nanoimprint lithography.	07
Q.5	<b>(a)</b>	Define negative resist and give examples.	03
-	<b>(b)</b>	Explain steps involved in preparation of resist for photolithograp	ohy. <b>04</b>
	(c)	Write note on Applications of X-ray Lithography.	07
		OR	
Q.5	<b>(a)</b>	Define positive resist and give examples.	03
-	<b>(b)</b>	Explain mask used for X-ray Lithography.	04
	(c)	Write note on Applications of Photolithography.	07